

48th International Spring Seminar on Electronics Technology

CONFERENCE PROGRAM

14:00 Arrival, registration, and accommodation 19:00 Welcome Reception, Dinner 21:00 Steering Committee meeting Thursday, 15th of May 08:30 Opening session of ISSE 2025 Welcome speech from the organizers Oliver Krammer, Attila Geczy	rner		
19:00 Welcome Reception, Dinner 21:00 Steering Committee meeting Thursday, 15th of May 08:30 Opening session of ISSE 2025 Welcome speech from the organizers	rner		
Thursday, 15 th of May 08:30 Opening session of ISSE 2025 Location: TRIBE Arena h Welcome speech from the organizers			
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Onver Krammer, Actin deezy			
08:45 Oral session I chaired by: O. Krammer and A. Geczy Location: TRIBE Arena h	all		
KN01 The APECS pilot line is powering the evolution of chiplet technologies Rolf Aschenbrenner (Fraunhofer IZM, Berlin)			
KN02 Sustainable electronics: what kind of sustainability? Pascal Xavier (Grenoble Alps University)			
S01 Metrology and Inspection Method Advancements Driven by the Advanced Packaging Mar Orsolya Keri (Semilab, Budapest)	Metrology and Inspection Method Advancements Driven by the Advanced Packaging Market		
Low Temperature Soldering (LTS) in the Electronics Industry: a Brief Review Balazs Illes (Budapest University of Technology and Economics)	·		
A technological Study examining the Implementation of sub-15 µm Finelines using photoimageable thick-film Pastes on Low Temperature Cofired Ceramics Uwe Ziegler (TU Ilmenau)	photoimageable thick-film Pastes on Low Temperature Cofired Ceramics		
10:45 Coffee break Sponsored by Balluff			
11:00 Oral session II chaired by: K. Nieweglowski and B. Illes Location: TRIBE Arena H	all		
KN03 Open-Source Educational Tools, past, present, future David J. Cuartielles Ruiz (Malmo University, Arduino)			

A93	Multi-material Additive Manufacturing of Electronic Circuits Cor Freeforming Technology with Molten Metal Printing	mbining ARBURG	i Plastic
A52	Daniel Straubinger (Hahn-Schickard) Investigation of PEDOT:PSS/Bismuth Telluride Composite for Fle Karol Rauch (Wroclaw University of Science and Technology)	xible Thermoco	uples
A30	Microstructural evolution of Sn-Cu Based Bi Alloyed Lead-free So Bela Bodi (Obuda University)	older at Low Coo	oling Rate
12:30	taran da antara da a	Location: TRIBE	Restaurant
13:30	Poster session I chaired by: P. Xavier and D. Cuartielles	Location: TRIBE	Arena &
A07	Dielectric Properties of BaFe12O19 Doped with SiO2 in the Low F Stanko Aleksic (Institute of Nuclear Sciences Vinca Belgrade)	Frequency Regio	n
A28	Novel Ceramic-Polymer Composite for Stereolithography with E	nhanced Therma	al Conductivity
	Petr Vesely (Czech Technical University in Prague)	h	
A42	Fabrication of Piezoelectric Composite Polymers Using Stereolith Jaroslav Pazourek (Czech Technical University in Prague)	nograpny	
	Synergistic Use of 3D Printing and Electrochemical Plating to Pro	oduce Electrical	Discharge
A49	Machining Electrodes		J
	Radek Tucek (Czech Technical University in Prague)		
A55	Additively Manufactured Electronic Circuits from Polymer Pastes Jonas Uricar (Czech Technical University in Prague)		
A400	Investigating the Mechanical Behaviour of Biodegradable Substi	rates	
A100	Oliver Krammer (Budapest University of Technology and Economics)		
A102	Lifetime Dependent Behaviour of Sulphite Gold Electrolyte Evelyn Napetschnig (Infineon Technologies Austria AG)		
F10	Biodegradable Sensors for Timber Construction Monitoring		
	Daniel Kranz (University of Applied Sciences Dresden) 3D Printed Circuit Boards from Recycled Plastics: Conductive Par	ttern Pronerties	
F26	Jakub Zdrahal (Czech Technical University in Prague)		
F41	Ultrasonic-Assisted Electrode Material Separation: Towards Indu	ustrial Applicatio	ons
	Anna Prazanova (Czech Technical University in Prague)		
F79	A Sustainable Temperature Monitoring System Powered by Sola Marius Mares (University POLITEHNICA of Bucharest)	r Cells and Supe	rcapacitors
F95	Soil degradation of sustainable PCB substrates in natural and co	ontrolled enviro	nments
F93	Csaba Farkas (Budapest University of Technology and Economics)		
F101	Current carrying capacity of PCB traces on PLA/Flax biodegradal	ble substrates	
	Adam Csapody (Budapest University of Technology and Economics) Enhancing the Manufacturability of Biodegradable PLA/Flax PCE	R Assemblies Thr	nugh Design
F108	Optimization	7,350,115,116,5 11.11	ough Design
	Gergo Havellant (Budapest University of Technology and Economics)		
F113	Effect of Water Absorption on the Low-Frequency Dielectric Pro	perties of Biode	gradable
F113	PLA/Flax PCB Substrates Zoltan Adam Tamus (Budapest University of Technology and Econom	nics)	
15:00	Coffee break Sponsored by Balluff		
15:15	Oral session III chaired by: D. Busek and K. Dusek	Location: TRIBE	l Arena
	Chiplets 1960-2030; Where We've Been & Where We're Going!		
KN04	Charles E. Bauer (TechLead Corporation)		

	Investigation of the Solder Thickness Effect on the Propagation Properties of Reactive		
C50	Multilayer Systems		
	Nesrine Jaziri (TU Ilmenau) Ultrasonic Bonding of AlCu Wire - An Advance to Reliable Interconnects for Power Modules		
C68	Chun-Hao Chen (National Yang Ming Chiao Tung University)		
	Location: TRIBE Arena &		
16:30	Poster session II chaired by: F. Steiner and J. Nicolics Dome		
D21	Study on Thermal Management Systems for Li-ion Cell Batteries		
Mirela Olteanu (Technical University of Cluj-Napoca)			
B72	Battery Preconditioning Methods for Electric Vehicles in Cold Climates: A Comparative Review		
	Adelina Ilies (Technical University of Cluj-Napoca)		
B77	Study on the Impact of Component Placement on the Thermal Performance of a Power Electronic Board		
D//	Alexandra Fodor (Technical University of Cluj-Napoca)		
D70	Influence of the Solder Joint Thermal Resistance on Thermal Performance of Power MOSFETs		
B78	Adrian Pietruszka (Gdynia Maritime University)		
C27	A Study on Stretchable Electrical Contacting Techniques for Embedded Chip Components		
U	Victoria Constance Kost (TU Dresden)		
C51	Advancements in Miniaturization of High-aspect Ratio Through Ceramic Microvias (TCµV) for		
CSI	High-Density Interconnect LTCC Interposer Nesrine Jaziri (TU Ilmenau)		
667	Reactive Bonding by the use of Nanolayer Stacks on LTCC Substrates		
C67	Steffen Wiese (Saarland University)		
C109	Development of a New Ceramic Package Design for Special Applications		
	Pavel Kopriva (Brno University of Technology)		
C118	Innovative Solutions for the Development of High-Performance ADS-B Receivers Vlad Hociung (University POLITEHNICA of Bucharest)		
	Modeling Electrochemical Migration of Sn-9Zn: Insights from Finite Difference and Finite		
E02	Element Methods		
	Ali Dayoub (Budapest University of Technology and Economics)		
E22	The AloT Infection Prediction in Vine Using Meteorological Condition		
	Mihaela Hnatiuc (Constanta Maritime University)		
E34	A Comparative Study of Short-Term Load Forecasting Methods for Improved Energy Management in Microgrids with Battery Storage		
234	Patarau Toma (Technical University of Cluj-Napoca)		
	Modeling and Analyzing Copper Dendrite Growth during Electrochemical Migration Using		
E46	Monte Carlo Simulation		
	Ali Gharaibeh (Budapest University of Technology and Economics)		
E54	Induction Motor Impedance Estimation Based on the Compressed Sensing Approach		
	Ondrej Kovac (Technical University of Kosice) Hardware in the Loop Simulation for Renewable Energy Resources		
E69	Nicolae Sarbu (Technical University of Cluj-Napoca)		
F70	Deployed Synthetic Lithium-Ion Battery for Improving Battery Diagnosis		
E70	Eliza Olariu (Technical University of Cluj-Napoca)		
	Magnetic Field Influence on the Content of Steroidal Glycoalkaloids and Derivatives under		
E99	Drought Conditions in Tomatoes		
40.00	Mirjana Damnjanovic (University of Novi Sad)		
19:00	Dinner Location: TRIBE Restaurant		

	Friday, 16 th of May		
08:30	Oral session IV chaired by: P. Lukacs and M. Kisic Location: TRIBE Arena		
KN05	Long Term Reliability of Light Emitting Diodes Gabor Harsanyi and Andras Poppe (Budapest University of Technology and Economics) Applications of Discontinuous Metal Thin Films to Electronics Packaging		
G81	James Morris (Portland State University) Fabrication of Conductive Contact on Graphene Monolayers via Direct Ink Writing Martin Sorm (University of West Bohemia)		
G96	Influence of Fe and Co Nanoparticle Flux Doping on Stress Relaxation Behaviour of Sn-3.5Ag Solder Joints Irina Wodak (TU Wien)		
10:15	Coffee break Sponsored by Balluff		
10:30	Poster session III chaired by: T. Blecha and A. Pietrikova Location: TRIBE Arena & Dome		
124	The Influence of Mechanical Strain on the Resistance of Thick Layers Printed on Textile Substrates Michalina Gruza (Wroclaw University of Science and Technology)		
129	Comparison of Manufacturing Methods for Skin Hydration Textile Sensor Jan Balaban (University of West Bohemia)		
136	Development of a Capacitive Measurement Setup for a Non-Contact Control System Tobias Tiedje (TU Dresden)		
140	Design and Implementation of a Tensile Testing Machine for Textronics Materials Characterization Afrodyta Daskalakis (Wroclaw University of Science and Technology)		
143	Analysing the Influence of Conductive Layer Morphology on Microwave Field Behaviour Olga Rac-Rumijowska (Wroclaw University of Science and Technology)		
138	Realization of Cost-Effective Supercapacitors Utilising Substitutable Materials Irina Madalina Burcea (National University of Science and Technology Politehnica Bucharest)		
148	Electrical Characterization of AlSiCu-on-AlSiTi/TiN Structured Contacts for Schottky Photodiodes Leonor Shala (Fraunhofer IPMS)		
156	A New Software Defined Radio Communication System Using 256-QAM Radu Gabriel Bozomitu ("Gheorghe Asachi" Technical University of Iasi)		
158	Enhanced Gas Monitoring for Automated Greenhouses Vlad Veliciu (Technical University of Cluj-Napoca)		
160	Development of an Intelligent EEG-Based System for Monitoring Environmental Impact on Human Neurophysiology Gombos Andreea (Technical University of Cluj-Napoca)		
I61	Bioimpedance Circuit Simulation for Real-Time Hydration Assessment in Athletic Performance Monitoring Pena Madalina (Technical University of Cluj-Napoca)		
166	Design and Testing of a Capacitive Sensor for Liquid Level Measurements Andrei Kiss (Technical University of Cluj-Napoca)		
182	MEMS Accelerometer as a Component for Increasing the Power Cutting Equipment Safety Slavomir Kardos (Technical University of Kosice)		
187	3-D Printed Galinstan-Based Capacitive Strain Sensor Milica Kisic (University of Novi Sad Novi Sad)		

189	Precise Positioning System for Autonomous Vehicles and Rosen Miletiev (Technical University of Sofia)	Intelligent Transport	
194	Low-Cost Drone-mounted Frequency-Modulated Continuous Wave Ground Penetrating Radar Mihaela Hnatiuc (Constanta Maritime University)		
198	Development of Fully Elastic Sensor Based on Conductive Deformation Sensing Milica Kisic (University of Novi Sad)	Hydrogel for Mechanical Multi-	
l117	Pectin-based Impedance Humidity Sensor Patrycja Suchorska-Wozniak (Wroclaw University of Science ar	nd Technology)	
l119	Respiratory Monitoring with Silicon Nanowires Rebeka Kiss (University of Debrecen)	-	
12:30	Lunch	Location: TRIBE Restaurant	
13:30	Oral session V chaired by: P. Markowski and G. Harsanyi	Location: TRIBE Arena	
B80	Comparative Study of Layout Effects on Thermal Management in PCB Hot-Plate Vlad Cristescu (Technical University of Cluj-Napoca)		
E45	Simulation of Temperature Distribution in Large-Area Joints in Power Electronics Peter Nemergut (Technical University of Kosice)		
F83	Power Electronics Solar Inverter on a Biosourced and Biodegradable Substrate – Thermal Study		
	Vincent Grennerat (University Grenoble Alpes)		
114	Vincent Grennerat (University Grenoble Alpes) Al-enhanced and automated indirect process monitoring Maedeh Nobari (Fraunhofer IPMS)	at the sensor edge	
114 15:00	Al-enhanced and automated indirect process monitoring	at the sensor edge	
	Al-enhanced and automated indirect process monitoring Maedeh Nobari (Fraunhofer IPMS)	at the sensor edge	
15:00	Al-enhanced and automated indirect process monitoring Maedeh Nobari (Fraunhofer IPMS) Break	at the sensor edge Location: Unicum House	
15:00 16:30	Al-enhanced and automated indirect process monitoring Maedeh Nobari (Fraunhofer IPMS) Break Bus Trip from TRIBE to Unicum House and Museum		

Saturday, 17 th of May			
09:00	Poster session IV chaired by: H. Wohlrabe and P. Vesely Location: TRIBE Arena & Dome		
D05	Development of a Low Budget Solar Simulator for Testing the Solar Radiation Effects Martin Hirman (University of West Bohemia)		
D12	Fabrication and Experimental Analysis of a Multi-Voltage Level Switching Circuit Gergo Kovacs (Technical University of Cluj-Napoca)		
D15	Effect of Fe and Bi Additives on Electrochemical Migration Behavior of SAC105 Marketa Klimtova (Czech Technical University in Prague)		
D16	Comparison of Thermal Impacts on Performance of LEDs Considering Lighting Fixture Type Denis Fros (Czech Technical University in Prague)		
D19	Design of Analog Front End for Measuring Bioimpedance		
D23	Influence of Stencil Thickness and Surface Finishes of Soldering Pads on the Formation of the Voids Inside Solder Joints Karel Dusek (Czech Technical University in Prague)		

	Impact of Prepreg Thickness and Thermal Stress on Thermomechanical Behavior of Printed		
D25	Circuit Board Substrates Daniel Kos (Croch Tachnical University in Prague)		
	Daniel Koc (Czech Technical University in Prague) Study of Dielectric Strength of Ceramic Substrates for Power Electronics		
D38	Jiri Hlina (University of West Bohemia)		
	Wetting Balance Test of Tin-Based Solder Alloys: Effect of Oxide Removal on Wetting		
D39	Performance		
	Iva Kralova (Czech Technical University in Prague)		
D44	Mechanical Strength of Aged Solder Joints: Impact of Plasma Treatment		
	Pavel Rous (University of West Bohemia) Space Charge Accumulation and Measurement Method for Insulation Materials		
D47	Frantisek Steiner (University of West Bohemia)		
	Performance Assessment of Commercial MOX Sensors in Elevated Hydrogen and Methane		
D53	Concentrations		
	Felix Stadermann (TU Dresden)		
D63	Investigation of the Solder Fluxes Activity by Measuring of the Contact Angle		
	Daniel Dzivy (Technical University of Kosice)		
D65	Modelling the Fault Injection of Sensor Interfaces in Automotive Electronics Nicolae Gross (University POLITEHNICA of Bucharest)		
	Stability of Embedded Solder Joints' Electrical Resistance		
D71	Tomas Lenger (Technical University of Kosice)		
	Characterization of Solder Flux by Synergic Combination of Gas Chromatography Coupled to		
D74	Mass Spectrometry and Fourier-Transform Infrared Spectroscopy		
	Dominik Pilnaj (Czech Technical University in Prague)		
D75	Degradation Mechanisms of LEDs Used in Residential Lighting		
	Bianka Forczek (Budapest University of Technology and Economics)		
D76	Stability of Embedded Polymer Thick-film Resistors in 3D Printed Structures Compared to FR4- based PCBs		
D/0			
	Igor Vehec (Technical University of Kosice)		
	Igor Vehec (Technical University of Kosice) Underfill Inspection and Testing in Surface Mount Technology: A Review of Diagnostic and		
D86	Igor Vehec (Technical University of Kosice) Underfill Inspection and Testing in Surface Mount Technology: A Review of Diagnostic and Analytic Methods		
D86	Underfill Inspection and Testing in Surface Mount Technology: A Review of Diagnostic and Analytic Methods Zbynek Plachy (Czech Technical University in Prague)		
	Underfill Inspection and Testing in Surface Mount Technology: A Review of Diagnostic and Analytic Methods Zbynek Plachy (Czech Technical University in Prague) Properties of Thin Films on 3D Printed Substrates		
D86	Underfill Inspection and Testing in Surface Mount Technology: A Review of Diagnostic and Analytic Methods Zbynek Plachy (Czech Technical University in Prague) Properties of Thin Films on 3D Printed Substrates David Busek (Czech Technical University in Prague)		
D90	Underfill Inspection and Testing in Surface Mount Technology: A Review of Diagnostic and Analytic Methods Zbynek Plachy (Czech Technical University in Prague) Properties of Thin Films on 3D Printed Substrates David Busek (Czech Technical University in Prague) Investigation of Electromigration in Cu-Sn Interfaces under the Condition of High Current		
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D90 D114 D116	Underfill Inspection and Testing in Surface Mount Technology: A Review of Diagnostic and Analytic Methods Zbynek Plachy (Czech Technical University in Prague) Properties of Thin Films on 3D Printed Substrates David Busek (Czech Technical University in Prague) Investigation of Electromigration in Cu-Sn Interfaces under the Condition of High Current Pulses Irina Wodak (TU Wien) Seebeck Coefficient Characterisation Using Innovative Set-up for Film Materials Piotr Markowski (Wroclaw University of Science and Technology)		
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D90 D114 D116 11:00 11:15 A17	Underfill Inspection and Testing in Surface Mount Technology: A Review of Diagnostic and Analytic Methods Zbynek Plachy (Czech Technical University in Prague) Properties of Thin Films on 3D Printed Substrates David Busek (Czech Technical University in Prague) Investigation of Electromigration in Cu-Sn Interfaces under the Condition of High Current Pulses Irina Wodak (TU Wien) Seebeck Coefficient Characterisation Using Innovative Set-up for Film Materials Piotr Markowski (Wroclaw University of Science and Technology) Coffee break Poster session V chaired by: G. Khatibi and B. Mihailescu Location: TRIBE Arena & Dome Effect of mechanochemical modification of Ag ₂ O particles on the electrical properties of Ag layers formed from Ag ₂ O pastes Alena Pietrikova (Technical University of Kosice) Development of Hydrosoluble Substrate with Low Surface Roughness Nora Tarpataki (Budapest University of Technology and Economics)		
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G33	Synthesis, Characterization, and Application of PVDF Thin Film Separator for Supercapacitors		
	Irina Burcea (National University of Science and Technology Politehnica Bucharest) Colour Sensitivity on the OLED Smartphone Display		
G64	Adrian Tulbure ("1 Decembrie 1918" University of Alba Iulia)		
	Comparison of Rectangular and Hexagonal Periodic Unit Cells for Modeling Plasmonic		
G85	Nanoparticle Arrays		
	Rebeka Kovacs (Budapest University of Technology and Economics)		
G107	Optical and Electrochemical Sensing with Gold Nanoparticles		
	Mate Kalman Stift (Budapest University of Technology and Economics) Single Live Cell Assays with Label-free Optical Biosensor for the Development of Diagnostic		
G110			
	Igor Sallai (Budapest University of Technology and Economics)		
	Advanced Noise Suppression Techniques in ECG Systems: Cor	mbining Right-Leg Drive (RLD)	
H59	Amplifiers with Digital Signal Processing (DSP)		
	Gombos Andreea (Technical University of Cluj-Napoca) Comparison of Signal Integrity Simulation Tools: HyperLynx N	vs. Keysight ADS on eMMC	
H62	Interfaces	7.8	
	Octavian Axinte (Technical University of Cluj-Napoca)		
1170	Improvement of Over-the-Air Antenna Performance Tests for	r Electric Vehicle Alternating	
H73	Current Chargers Pumpys a Tuba Sovon Mison (Ozvogin University)		
	Rumeysa Tuba Seven lyison (Ozyegin University) Considerations Regarding the Study of EMC Filters Applied to Power Inverters		
H104	Tudor Bancu (Technical University of Cluj-Napoca)		
H105	Textile-Based Flexible Coaxial Cable with Improved EMC		
	Jan Handrejch (University of West Bohemia)		
J09	Improving Atomic Layer Deposition Process of Silicon Oxide (SiO2) Long Lei (Fraunhofer IPMS)		
124	Two-in-one IoT Device for Product Pricing and Inventory Monitoring		
J21	Rajmond Jano (Technical University of Cluj-Napoca)		
104	International Collaborative Hands-on Activities on Advanced	Electronics and Photonics for	
J91	Higher Education Using 3D Printing Techniques Krzysztof Nieweglowski (TU Dresden)		
	Sustainable Design, Manufacturing and Development of E-tra	ansportation Electronics Training	
J111	in the TRIREME project	-	
	Balint Medgyes (Budapest University of Technology and Economi	cs)	
13:00	Lunch	Location: Conference Venue	
14:00	Oral session VI chaired by: K. Dusek and A. Tulbure	Location: Location: TRIBE Arena	
D18	Machine Learning Modelling for Electronic Reliability Analysi	s in Solder Joints	
	Cristian Garzon Alfonso (University of Florence) A Brief Review on Electromigration Behaviours of Solder Joints under Electrothermal Load		
D103	Zoltan Tafferner (Budapest University of Technology and Econom		
	Effect of Plasma Gas onto Epoxy Mold Compound Adhesion w		
D115 Modules			
45-00	Mario Sprenger (Institute for Factory Automation and Production		
15:00	Closing ceremony - invitation to ISSE 2026	Location: TRIBE Arena	
15:30	Bus Trip from TRIBE to docks		

16:00	Danube Boat Trip w. open bar and snacks	Location: Daube (from Infopark)
18:00	Leaving the boat and walk from docks to University (10 min)	
18:00	Steering Committee Meeting	Location: BME I building IB019
18:30	Arrival at the Gala Dinner, open bar	Location: BME I building main hall
19:00	Quartetto Speranza (concert) and Awarding Session	Location: BME I building IB028
20:00	Dinner	Location: BME I building hall

	Sunday, 18 th of May	
Farewell; End of conference		

09:00